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Bib Data Sheet

**CONFIRMATION NO. 4031** 

	SERIAL NUMBER 10/693,896	FILING OR 371(c) DATE 10/28/2003 RULE	C	CLASS GRO		OUP ART UNIT 2813		ATTORNEY DOCKET NO. CHEN3595/EM	
	Jau-Shoung Chen, Jubei City, TAIWAN; Su Tao, Kaohsiung, TAIWAN; CONTINUING DATA **********************************								
	Foreign Priority claimed  35 USC 119 (a-d) conditions  met  Verified and  Acknowledged  Examiner's Signature  Allowance  Initials			STATE OR COUNTRY TAIWAN			TOT/ CLAII 13	MS	INDEPENDENT CLAIMS 1
	ADDRESS 23364								
. 1	TITLE Wafer bumping process with solder balls bonded to under bump metallurgy layer formed over active surface by forming flux on solder ball surfaces and reflowing the solder								
	FILING FEE FEE RECEIVED No.	NG FEE FEES: Authority has been given in Paper CEIVED No to charge/credit DEPOSIT ACCOUNT				All Fees  1.16 Fees (Filing)  1.17 Fees (Processing Ext. of time)  1.18 Fees (Issue)  Other  Credit			